

INFORMATION DISCLOSURE
CITATION IN AN
APPLICATION



(PTO-1449)

ATTY. DOCKET NO.
004066
USA/Consilium/Consilium

SERIAL NO.
09/363,966

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Technology Center 2100

APPLICANT
John F. ARACKAPARAMBIL et al.

FILING DATE
July 29, 1999

GROUP
2125

U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PUBLICATION / PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,889,991	03/30/99	Consolatti et al.			12/06/96
	6,183,345 B1	02/06/01	Kamono et al.			03/20/98
	6,253,366 B1	06/26/01	Mutschler, III			03/31/99
	6,298,470 B1	10/02/01	Breiner et al.			04/15/99

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EXAMINER'S INITIALS	PUBLICATION / PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	WO 01/52055 A3	07/19/01	WO			X	
	WO 01/57823 A2	08/09/01	WO			X	
	EP 1 182 526 A2	02/27/02	Europe			X	
	WO 02/17150 A1	02/28/02	WO			X	
	WO 02/33737 A2	04/25/02	WO			X	

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	Chemali, Chadi El, James Moyne, Kareemullah Khan, Rock Nadeau, Paul Smith, John Colt, Jonathan Chapple-Sokol, and Tarun Parikh. July/August 2000. "Multizone Uniformity Control of a Chemical Mechanical Polishing Process Utilizing a Pre- and Postmeasurement Strategy." J. Vac. Sci. Technol. A, Vol. 18(4). pp. 1287-1296. American Vacuum Society.
	Jensen, Alan, Peter Renteln, Stephen Jew, Chris Raeder, and Patrick Cheung. June 2001. "Empirical-Based Modeling for Control of CMP Removal Uniformity." Solid State Technology, Vol. 44, No. 6, pp. 101-102, 104, 106. Cowan Publ. Corp.: Washington, D.C.
	Sarfaty, Moshe, Arulkumar Shanmugasundram, Alexander Schwarm, Joseph Paik, Jimin Zhang, Rong Pan, Martin J. Seamons, Howard Li, Raymond Hung, and Suketu Parikh. April/May 2002. "Advance Process Control Solutions for Semiconductor Manufacturing." IEEE/SEMI Advanced Semiconductor Manufacturing Conference. pp. 101-106.
	October 4, 2002. International Search Report from PCT/US01/22833.
	October 23, 2002. International Search Report from PCT/US01/27406.
	November 7, 2002. International Search Report from PCT/US02/19061.
	November 11, 2002. International Search Report from PCT/US02/19117.
	November 12, 2002. International Search Report from PCT/US02/19063.

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9/16/04

5/28/03

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EXAMINER'S INITIALS	PUBLICATION / PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	5,270,222	12/14/93	Moslehi			12/31/90
	5,375,064	12/20/94	Bollinger			12/02/93
	5,599,423	02/04/97	Parker et al.			06/30/95
	5,844,554	12/01/98	Geller et al.			09/17/96

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EXAMINER'S INITIALS	PUBLICATION / PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
	WO 95/34866	12/21/95	WO			X	
	WO 98/45090	10/15/98	WO			X	
	EP 0 881 040 A2	12/02/98	Europe			X	
	WO 99/25520	05/27/99	WO			X	
	WO 00/54325	09/14/00	WO			X	
	EP 1 066 925 A2	01/10/01	Europe			X	
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	Hu, Albert, Kevin Nguyen, Steve Wong, Xiuhua Zhang, Emanuel Sachs, and Peter Renteln. 1993. "Concurrent Deployment of Run by Run Controller Using SCC Framework." IEEE/SEMI International Semiconductor Manufacturing Science Symposium. pp. 126-132.
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	Suzuki, Junichi and Yoshikazu Yamamoto. 1998. "Toward the Interoperable Software Design Models: Quartet of UML, XML, DOM and CORBA." Proceedings IEEE International Software Engineering Standards Symposium. pp. 1-10.
	Klein, Bruce. June 1999. "Application Development: XML Makes Object Models More Useful." Informationweek. pp. 1A-6A.
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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
snb	3,767,900	10/23/73	Chao et al.			06/23/71
snb	3,920,965	11/18/75	Sohrwardy			03/04/74
snb	4,368,510	01/11/83	Anderson			10/20/80
snb	4,616,308	10/07/86	Morshedi et al.			12/02/85
snb	4,663,703	05/05/87	Axelby et al.			10/02/85
snb	5,347,446	09/13/94	Iino et al.			02/10/92
snb	5,519,605	05/21/96	Cawfield			10/24/94
snb	6,128,016	10/03/00	Coelho et al.			12/20/96
snb	6,219,711	04/17/01	Chari			10/01/97
snb	6,249,712	06/19/01	Boiquaye			09/25/96
snb	6,278,899	08/21/01	Piche et al.			10/06/98
snb	2001/0039462	11/08/01	Mendez et al.			04/02/01
snb	2001/0040997	11/15/01	Tsap et al.			05/15/01
snb	2002/0128805	09/12/02	Goldman et al.			12/26/00

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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
snb	EP 1 067 757	01/10/01	Europe			X	
snb	WO 01/33277	05/10/01	WO			X	
snb	WO 02/31613 A2	04/18/02	WO			X	
snb	WO 02/31613 A3	04/18/02	WO			X	

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snb	Levine, Martin D. 1985. <i>Vision in Man and Machine</i> . New York: McGraw-Hill, Inc. pp. ix-xii, 1-58.
snb	Pilu, Maurizio. September 2001. "Undoing Page Curl Distortion Using Applicable Surfaces." <i>IEEE International Conference on Image Processing</i> . Thessalonica, Greece.
snb	23 May 2003. Written Opinion for PCT/US01/24910.

EXAMINER <i>Garlet</i>	DATE CONSIDERED <i>9/16/03</i>
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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
sn0	5,901,313	05/04/99	Wolf et al.			09/02/97
sn0	6,002,989	12/14/99	Shiba et al.			04/01/97
sn0	6,094,688	07/25/00	Mellen-Garnett et al.			03/12/98
sn0	6,340,602	01/22/02	Johnson et al.			02/12/01
sn0	6,345,288	02/05/02	Reed et al.			05/15/00
sn0	6,368,879	04/09/02	Toprac			09/22/99
sn0	US-2002/0107604	08/08/02	Riley et al.			12/06/00
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sn0	6,482,660	11/19/02	Conchieri et al.			03/19/01
sn0	6,567,717	05/20/03	Krivokapic et al.			01/19/00

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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
sn0	WO 99/59200	11/18/99	WIPO			X	
sn0	WO 01/52319	07/19/01	WIPO			X	

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sn0	Williams, Randy, Dadi Gudmundsson, Kevin Monahan, Raman Nurani, Meryl Stoller and J. George Shanthikumar. October 1999. "Optimized Sample Planning for Wafer Defect Inspection," <i>Semiconductor Manufacturing Conference Proceedings, 1999 IEEE International Symposium on Santa Clara, CA</i> . Piscataway, NJ. pp. 43 - 46.
sn0	23 July 2003. Invitation to Pay Additional Fees and Communication Relating to the Results of the Partial International Search for PCT/US02/19116.
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sn0	20 August 2003. Written Opinion for PCT/US01/22833.

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Barclay

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7/16/03

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SHEET 1 OF 2

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John F. ARACKAPARAMBIL et al.

FILING DATE
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U.S. PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
snb	4,207,520	06/10/80	Flora et al.			04/06/78
snb	4,209,744	06/24/80	Gerasimov et al.			03/27/78
snb	4,609,870	09/02/86	Lale et al.			09/13/84
snb	4,755,753	07/05/88	Chern			07/23/86
snb	5,427,878	06/27/95	Corliss			05/16/94
snb	5,534,289	07/09/96	Bilder et al.			01/03/95
snb	5,867,389	02/02/99	Hamada et al.			11/26/96
snb	6,041,263	03/21/00	Boston et al.			10/01/97
snb	6,077,412	06/20/00	Ting et al.			10/30/98
snb	6,271,670	08/07/01	Caffey			02/08/99
snb	6,400,162	06/04/02	Mallory et al.			07/21/00
snb	US 2002/0077031	06/20/02	Johansson et al.			07/06/01
snb	6,442,496	08/27/02	Pasadyn et al.			08/08/00
snb	6,563,308	05/13/03	Nagano et al.			03/27/01
snb	6,587,744	07/01/03	Stoddard et al.			06/20/00

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EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No
snb	WO 01/11679	02/15/01	WIPO			X	
snb	WO 01/080306	10/25/01	WIPO			X	

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snb	Miller, G. L., D. A. H. Robinson, and J. D. Wiley. July 1976. "Contactless measurement of semiconductor conductivity by radio frequency-free-carrier power absorption." <i>Rev. Sci. Instrum.</i> , Volume 47, No. 7. pp. 799 - 805.
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snb	2000. "Microsense II Capacitance Gaging System." www.adetech.com . 2000.

EXAMINER

Haidich

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9/16/04

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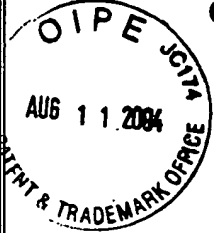
FOREIGN PATENT DOCUMENTS

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						Yes	No

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

snv	El Chemali, Chadi et al. July/August 2000. "Multizone uniformity control of a chemical mechanical polishing process utilizing a pre- and postmeasurement strategy." <i>J. Vac. Sci. Technol.</i> Volume 18, No. 4. pp. 1287 - 1296, July/August 2000.
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snv	2002. "Microsense II - 5810: Non-Contact Capacitance Gaging Module." www.adetech.com .
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snl	"NanoMapper wafer nanotopography measurement by ADE Phase Shift." http://www.phase-shift.com/nanomap.shtml . 12/9/03
snb	"Wafer flatness measurement of advanced wafers." http://www.phase-shift.com/wafer-flatness.shtml . 12/9/03
snv	"ADE Technologies, Inc. 6360." http://www.adetech.com/6360.shtml . 12/9/03
snb	"3D optical profilometer MicroXAM by ADE Phase Shift." http://www.phase-shift.com/microxam.shtml . 12/9/03
snv	"NanoMapper FA factory automation wafer nanotopography-measurement." http://www.phase-shift.com/nanomapperfa.shtml . 12/9/03
EXAMINER	DATE CONSIDERED
Gardner	9/10/04


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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
	4,901,218	02/13/90	Cornwell			03/04/88	
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	5,369,544	11/29/94	Mastrangelo			04/05/93	
	5,427,878	06/27/95	Corliss			05/16/94	
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	5,838,951	11/17/98	Song			08/28/96	
	5,859,777	01/12/99	Yokoyama et al.			05/13/97	
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	5,871,805	02/16/99	Lemelson			04/08/96	
	5,912,678	06/15/99	Saxena et al.			04/14/97	
	5,926,690	07/20/99	Toprac et al.			05/28/97	
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	6,150,270	11/21/00	Matsuda et al.			01/07/99	
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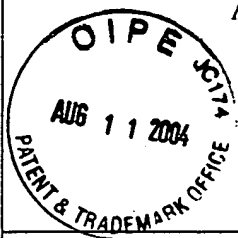
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EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
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	6,212,961 B1	04/10/01	Dvir			02/11/99	
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	6,355,559 B1	03/12/02	Havemann et al.			11/03/00	
	6,363,294 B1	03/26/02	Coronel et al.			12/29/98	
	6,391,780 B1	05/21/02	Shih et al.			08/23/99	
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	6,492,281 B1	12/10/02	Song et al.			09/22/00	
	6,495,452 B1	12/17/02	Shih			08/18/99	
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EXAMINER <i>Haley</i>				DATE CONSIDERED <i>9/16/04</i>			

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U.S. PATENT DOCUMENTS

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	2003/0017256 A1	01/23/03	Shimane			06/12/02
	6,515,368 B1	02/04/03	Lopatin et al.			12/07/01
	6,517,414 B1	02/11/03	Tobin et al.			03/10/00
	6,528,409 B1	03/04/03	Lopatin et al.			04/29/02
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	6,540,591 B1	04/01/03	Pasady et al.			04/18/01
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Donland

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9/16/04

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INFORMATION DISCLOSURE
CITATION IN AN
APPLICATION
(PTO-1449)

ATTY. DOCKET NO.
004066
USA/Consilium/Consilium

SERIAL NO.
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APPLICANT
John F. ARACKAPARAMBIL Technology Center 2100

FILING DATE
July 29, 1999

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		APPLICANT John F. ARACKAPARAMBIL et al.	
		FILING DATE July 29, 1999	GROUP 2125
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